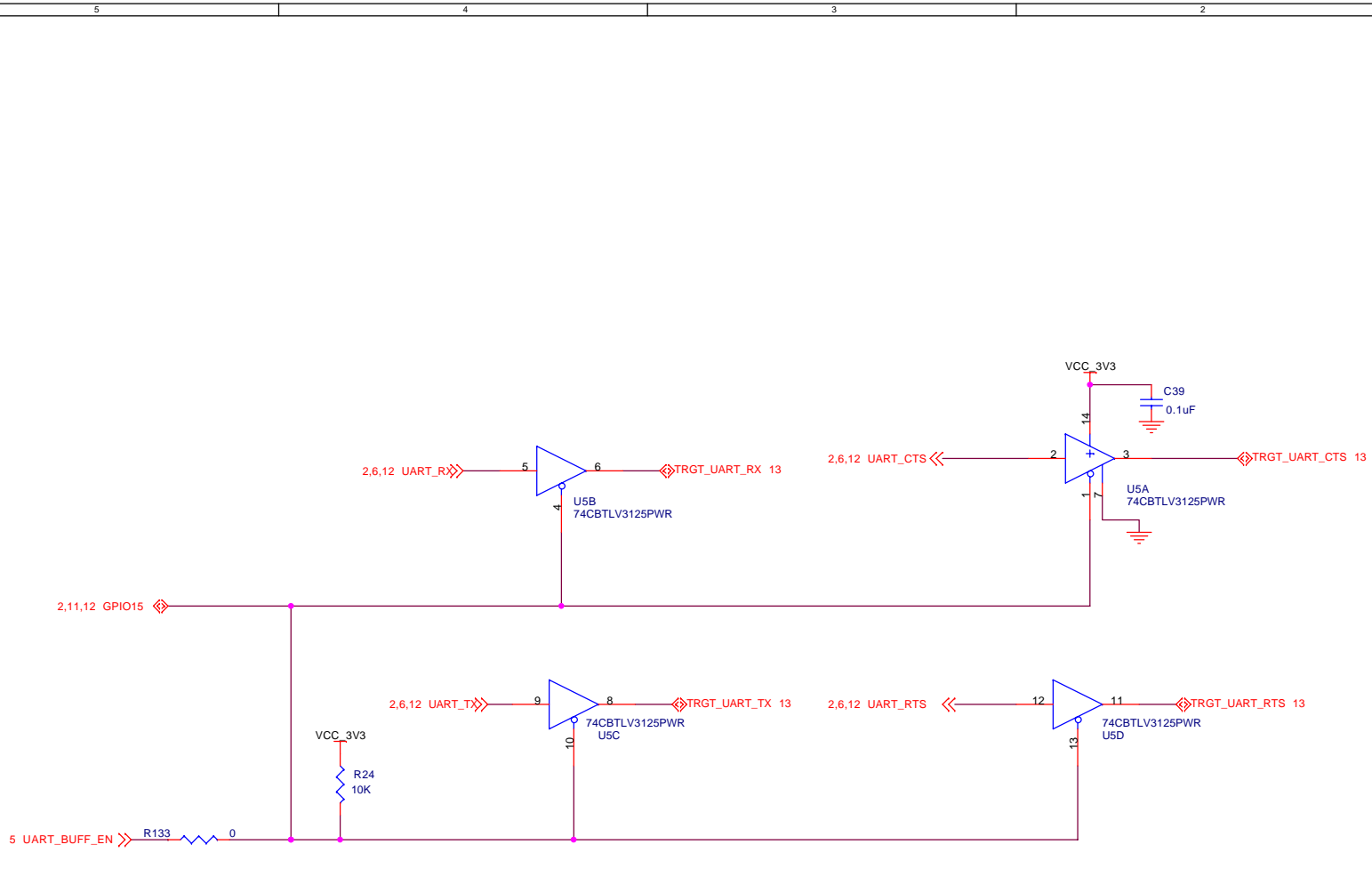
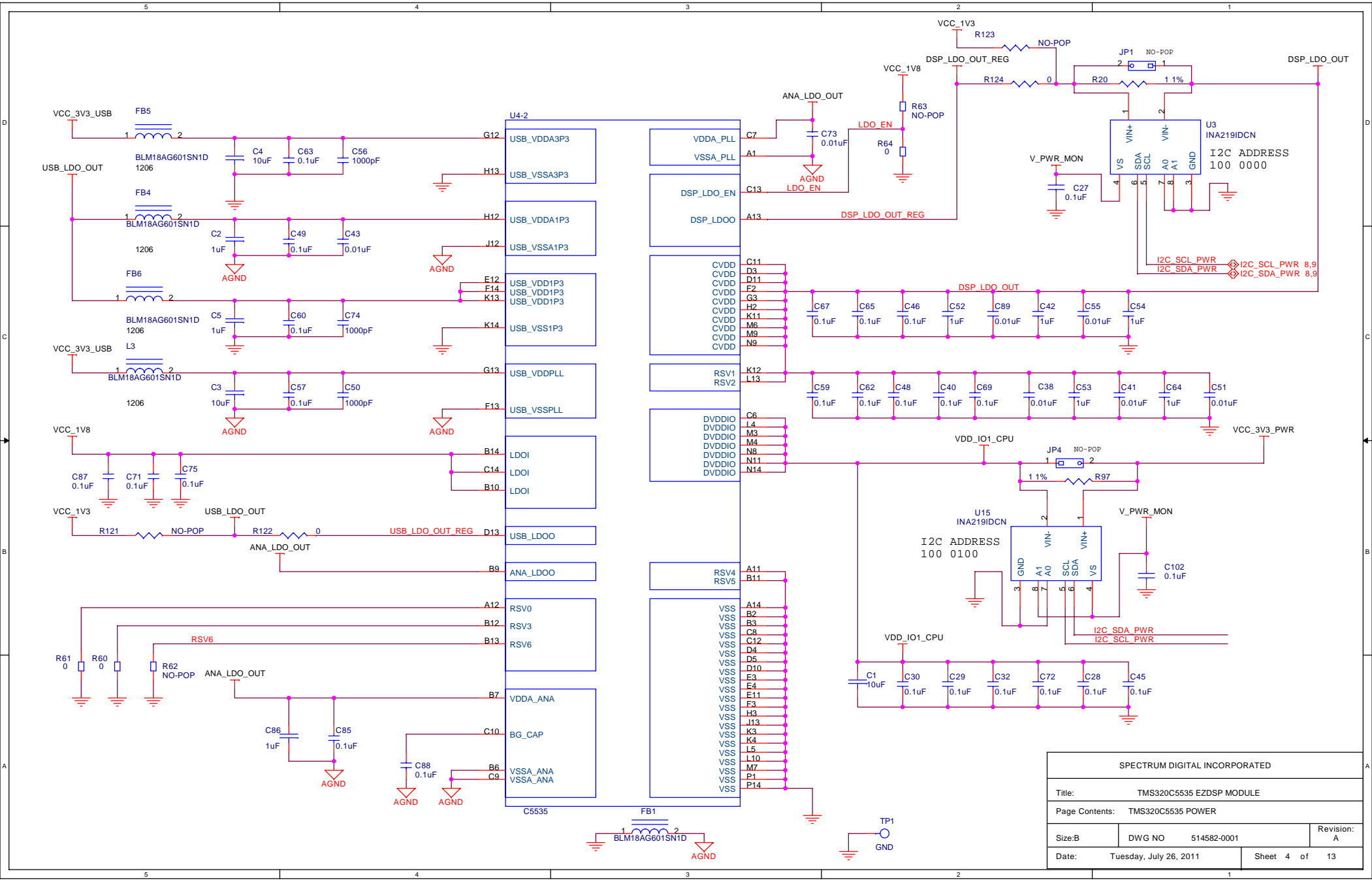


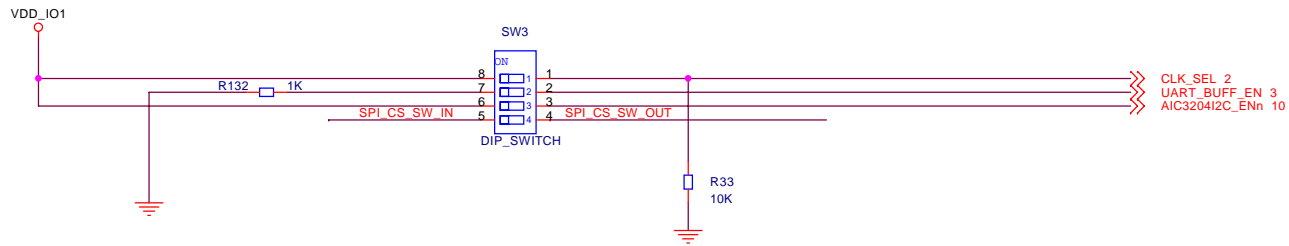
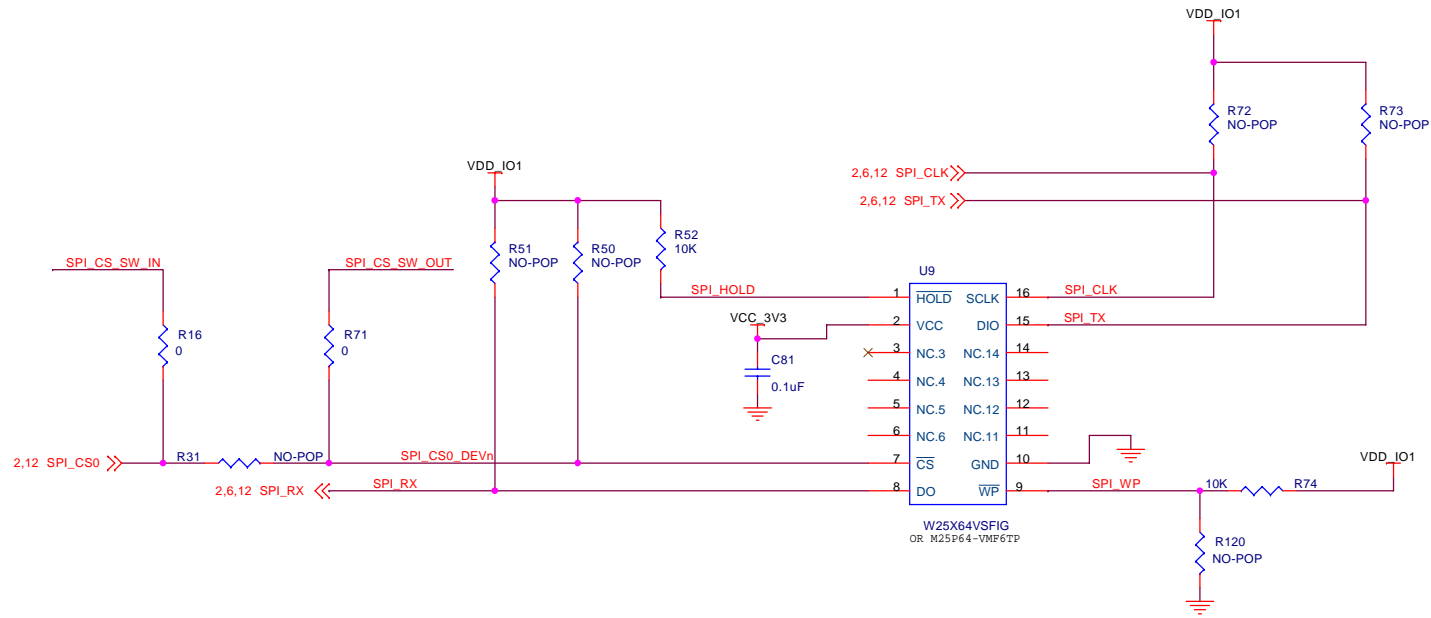
| SPECTRUM DIGITAL INCORPORATED              |                       |             |             |
|--|-----------------------|-------------|-------------|
| Title: TMS320C5535 EZDSP MODULE            |                       |             |             |
| Page Contents: GPIO, MMC-SD, SPI, I2C, I2S |                       |             |             |
| Size: B                                    | DWG NO                | 514582-0001 | Revision: B |
| Date:                                      | Friday, July 22, 2011 | Sheet 2 of  | 13          |



|                                 |                       |             |             |
|---------------------------------|-----------------------|-------------|-------------|
| SPECTRUM DIGITAL INCORPORATED   |                       |             |             |
| Title: TMS320C5535 EZDSP MODULE |                       |             |             |
| Page Contents: UART BUFFER      |                       |             |             |
| Size: B                         | DWG NO                | 514582-0001 | Revision: A |
| Date:                           | Friday, July 22, 2011 | Sheet 3 of  | 13          |



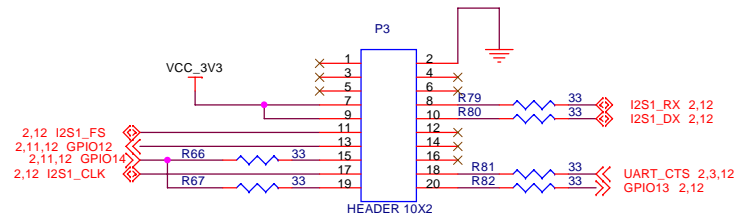
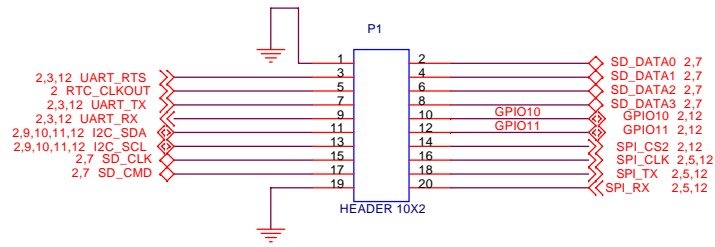
|                                  |                     |             |  |
|----------------------------------|---------------------|-------------|--|
| SPECTRUM DIGITAL INCORPORATED    |                     |             |  |
| Title: TMS320C5535 EZDSP MODULE  |                     |             |  |
| Page Contents: TMS320C5535 POWER |                     |             |  |
| Size: B                          | DWG NO: 514582-0001 | Revision: A |  |
| Date: Tuesday, July 26, 2011     | Sheet 4 of 13       |             |  |



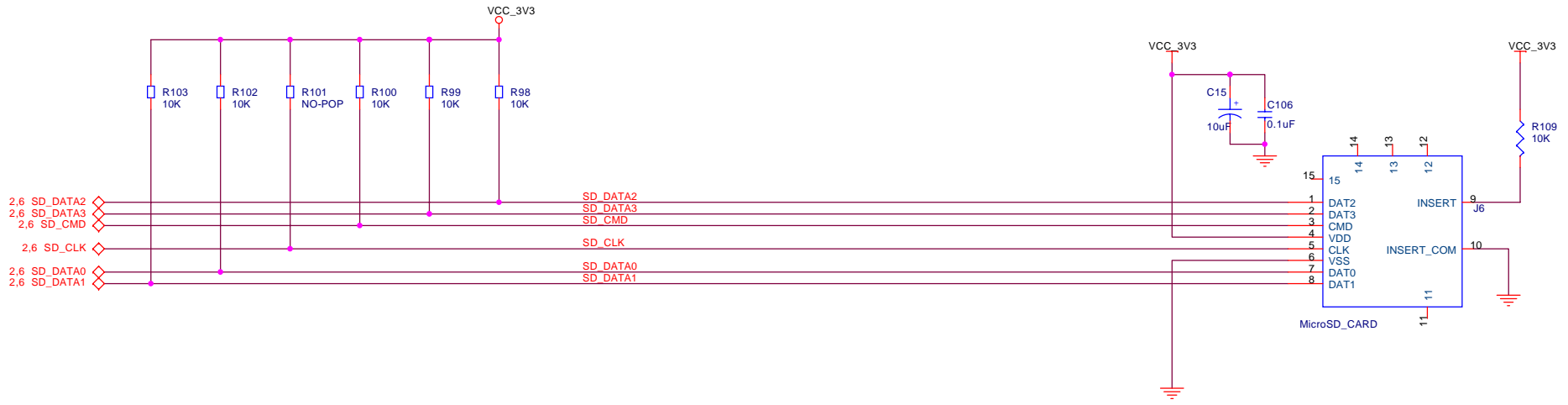
DIP Switch Defaults:  
 CLK\_SEL = OFF (pulled down)  
 UART\_BUFF\_EN = ON (pulled down)  
 AIC3204I2C\_ENn = OFF (pulled down)

|                                 |                        |             |               |
|---------------------------------|------------------------|-------------|---------------|
| SPECTRUM DIGITAL INCORPORATED   |                        |             |               |
| Title: TMS320C5535 EZDSP MODULE |                        |             |               |
| Page Contents: SPI FLASH        |                        |             |               |
| Size: B                         | DWG NO                 | 514582-0001 | Revision: C   |
| Date:                           | Tuesday, July 26, 2011 |             | Sheet 5 of 13 |

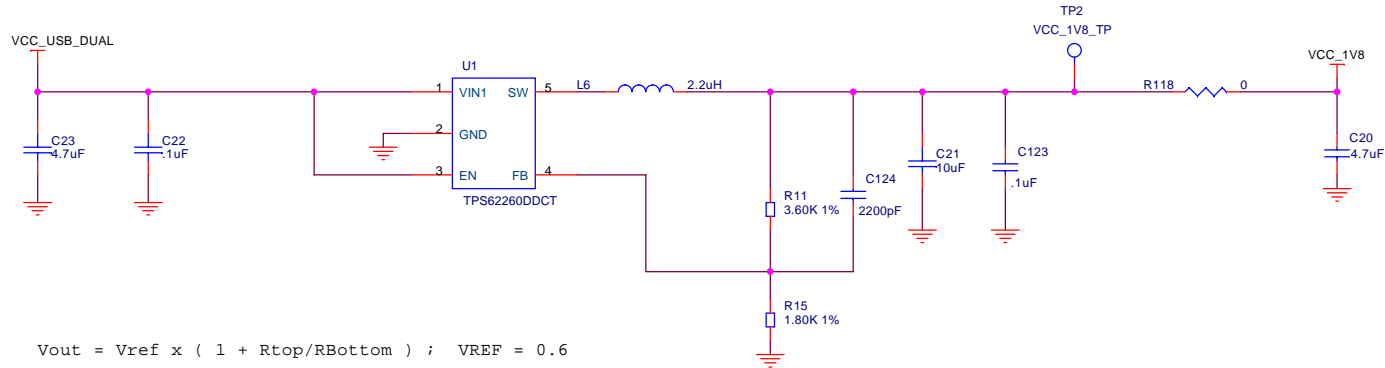
NOTE: DIMENSIONS AND LOCATIONS OF THESE CONNECTORS MUST MEET SPECIFICATION FOR INTERFACE MODULES



|                                   |                       |             |             |
|-----------------------------------|-----------------------|-------------|-------------|
| SPECTRUM DIGITAL INCORPORATED     |                       |             |             |
| Title: TMS320C5535 EZDSP MODULE   |                       |             |             |
| Page Contents: CC BOARD INTERFACE |                       |             |             |
| Size: B                           | DWG NO                | 514582-0001 | Revision: A |
| Date:                             | Friday, July 22, 2011 | Sheet 6 of  | 13          |

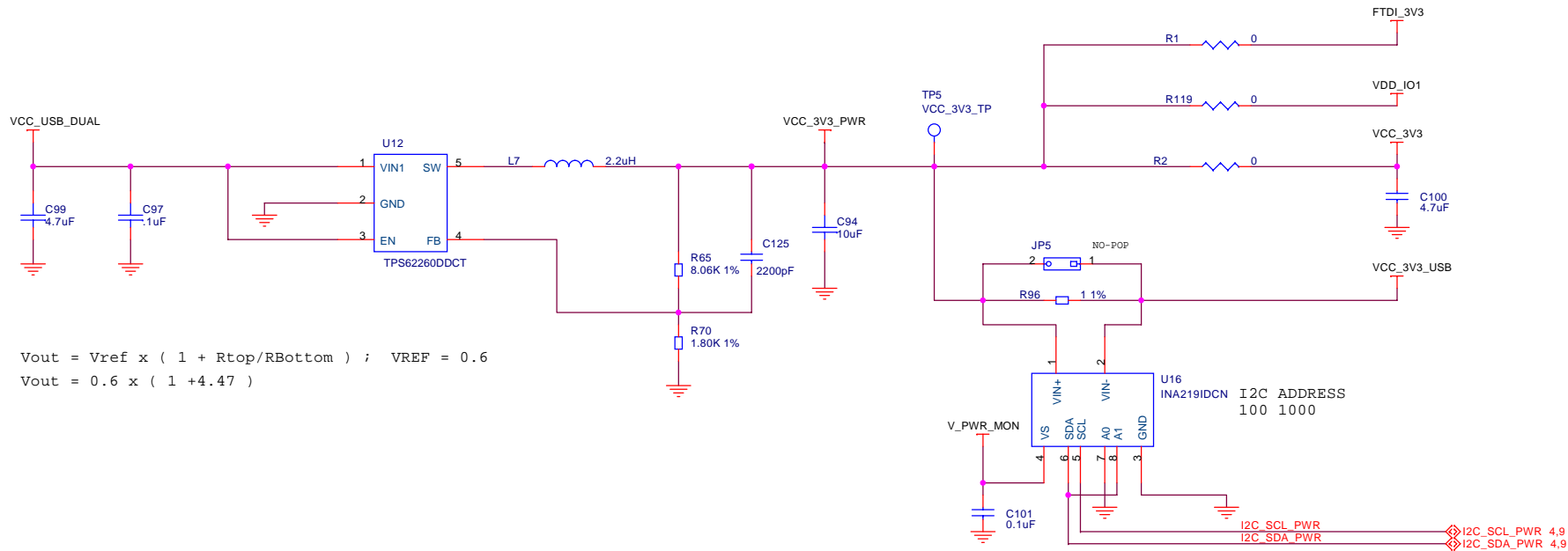


|                                   |                       |             |             |
|-----------------------------------|-----------------------|-------------|-------------|
| SPECTRUM DIGITAL INCORPORATED     |                       |             |             |
| Title: TMS320C5535 EZDSP MODULE   |                       |             |             |
| Page Contents: MICRO SD CONNECTOR |                       |             |             |
| Size: B                           | DWG NO                | 514582-0001 | Revision: A |
| Date:                             | Friday, July 22, 2011 | Sheet 7 of  | 13          |



$$V_{out} = V_{ref} \times ( 1 + R_{top}/R_{Bottom} ) ; \quad V_{REF} = 0.6$$

$$V_{out} = 0.6 \times ( 1 + 2 )$$

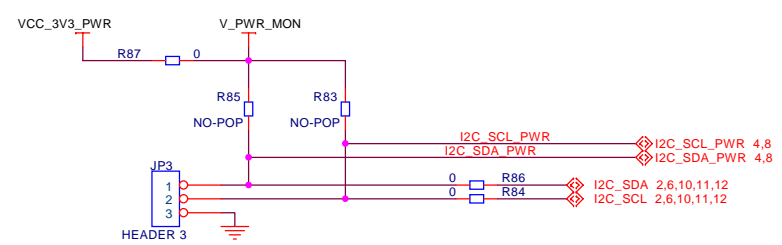
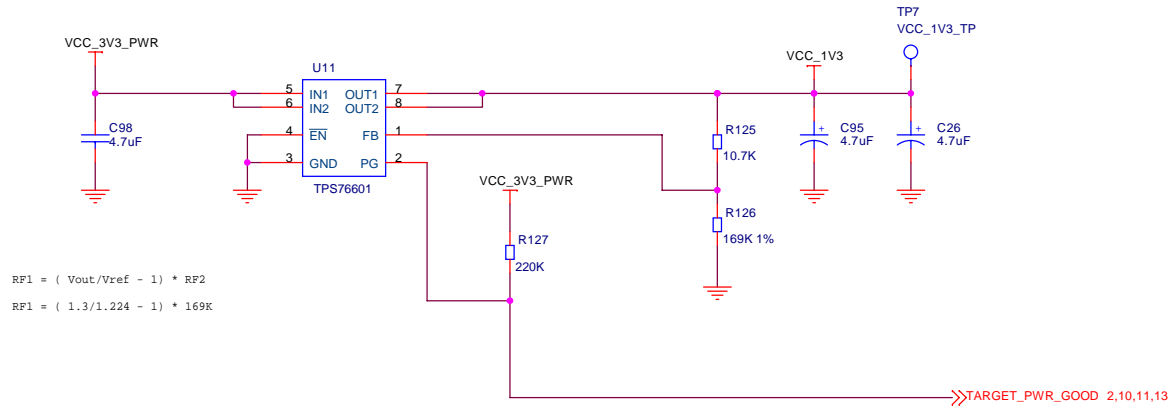


$$V_{out} = V_{ref} \times ( 1 + R_{top}/R_{Bottom} ) ; \quad V_{REF} = 0.6$$

$$V_{out} = 0.6 \times ( 1 + 4.47 )$$

|                                 |        |               |             |
|---------------------------------|--------|---------------|-------------|
| SPECTRUM DIGITAL INCORPORATED   |        |               |             |
| Title: TMS320C5535 EZDSP MODULE |        |               |             |
| Page Contents: POWER MANAGEMENT |        |               |             |
| Size: B                         | DWG NO | 514582-0001   | Revision: C |
| Date: Tuesday, July 26, 2011    |        | Sheet 8 of 13 |             |

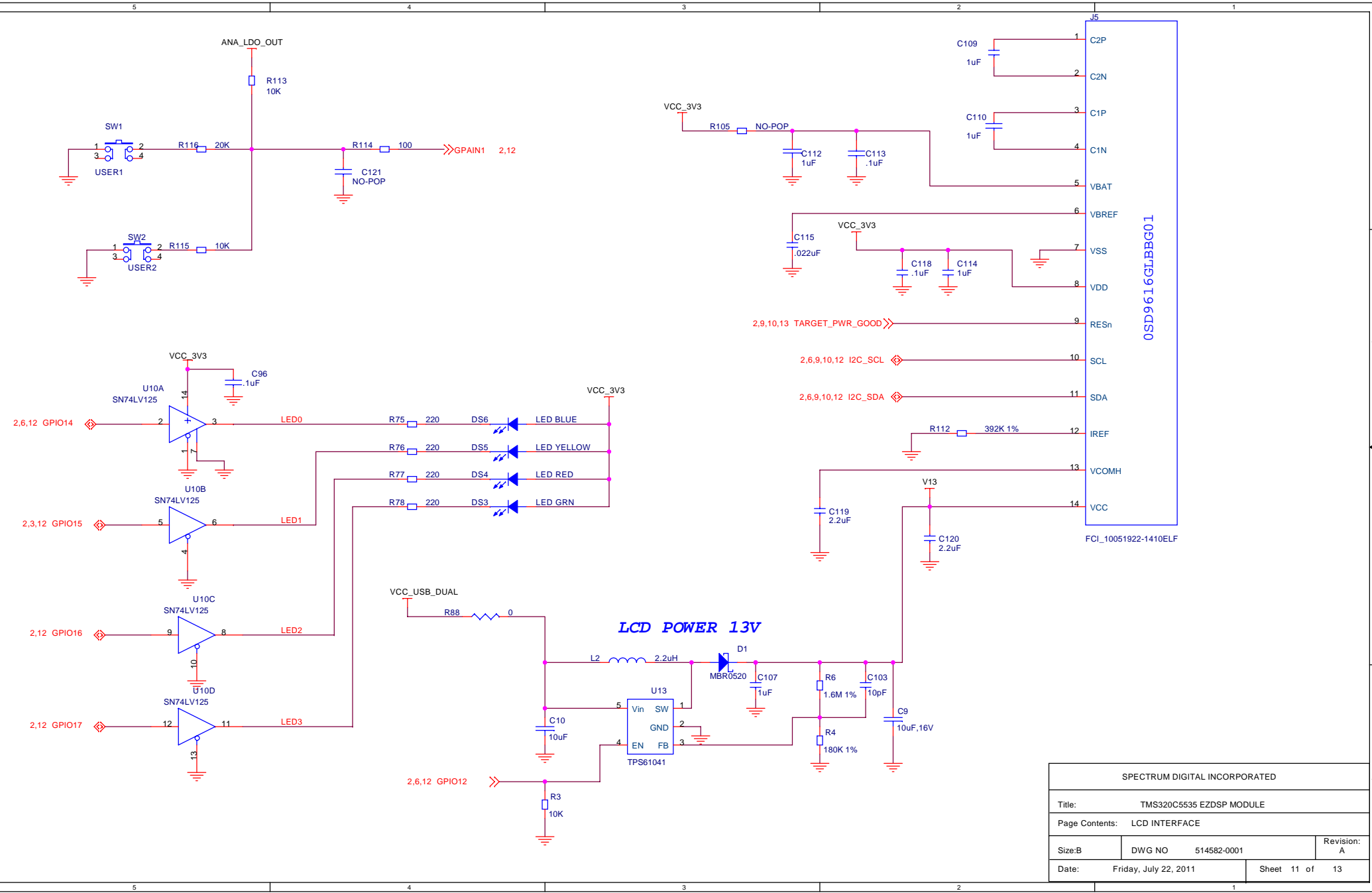




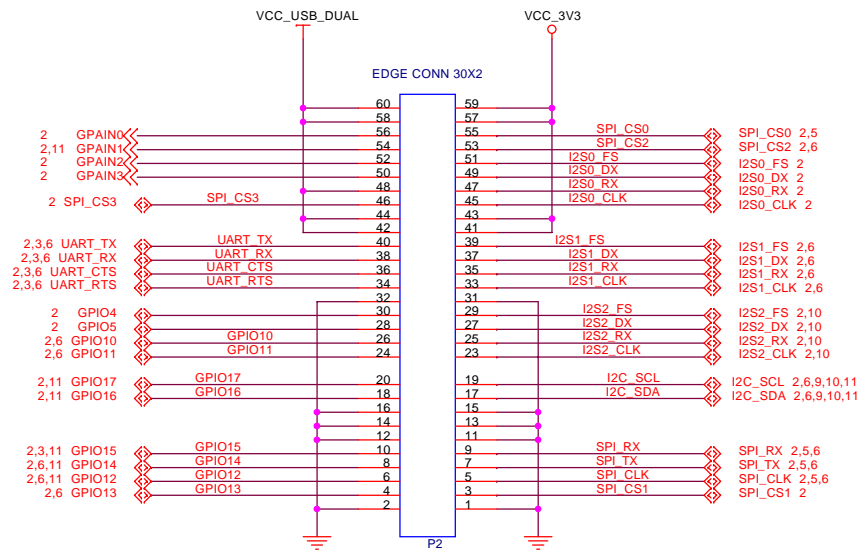
**Power Monitor I2C Probe Point Headers**

|                                 |                       |             |             |
|---------------------------------|-----------------------|-------------|-------------|
| SPECTRUM DIGITAL INCORPORATED   |                       |             |             |
| Title: TMS320C5535 EZDSP MODULE |                       |             |             |
| Page Contents: POWER MANAGEMENT |                       |             |             |
| Size: B                         | DWG NO                | 514582-0001 | Revision: A |
| Date:                           | Friday, July 22, 2011 | Sheet 9     | of 13       |





|                                 |                     |             |  |
|---------------------------------|---------------------|-------------|--|
| SPECTRUM DIGITAL INCORPORATED   |                     |             |  |
| Title: TMS320C5535 EZDSP MODULE |                     |             |  |
| Page Contents: LCD INTERFACE    |                     |             |  |
| Size: B                         | DWG NO: 514582-0001 | Revision: A |  |
| Date: Friday, July 22, 2011     | Sheet 11 of 13      |             |  |



|                                     |                       |             |             |
|-------------------------------------|-----------------------|-------------|-------------|
| SPECTRUM DIGITAL INCORPORATED       |                       |             |             |
| Title: TMS320C5535 EZDSP MODULE     |                       |             |             |
| Page Contents: EXPANSION CONNECTORS |                       |             |             |
| Size: B                             | DWG NO                | 514582-0001 | Revision: A |
| Date:                               | Friday, July 22, 2011 | Sheet 12 of | 13          |



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